

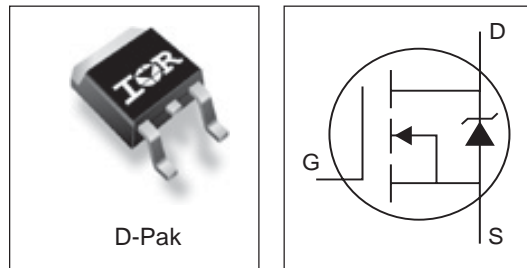
- N-Channel Application-Specific MOSFETs
- Ideal for CPU Core DC-DC Converters
- Low Conduction Losses
- Low Switching Losses
- Minimizes Parallel MOSFETs for high current applications
- 100% R<sub>G</sub> Tested

**Description**

This new device employs advanced HEXFET Power MOSFET technology to achieve an unprecedented balance of on-resistance and gate charge. The reduced conduction and switching losses make it ideal for high efficiency DC-DC converters that power the latest generation of microprocessors.

The IRLR8103V has been optimized for all parameters that are critical in synchronous buck converters including R<sub>DS(on)</sub>, gate charge and Cdv/dt-induced turn-on immunity. The IRLR8103V offers an extremely low combination of Q<sub>sw</sub> & R<sub>DS(on)</sub> for reduced losses in both control and synchronous FET applications.

The package is designed for vapor phase, infra-red, convection, or wave soldering techniques. Power dissipation of greater than 2W is possible in a typical PCB mount application.



**DEVICE CHARACTERISTICS** ⑤

	<b>IRLR8103V</b>
R <sub>DS(on)</sub>	7.9 mΩ
Q <sub>G</sub>	27 nC
Q <sub>SW</sub>	12 nC
Q <sub>OSS</sub>	29nC

**Absolute Maximum Ratings**

Parameter		Symbol	IRLR8103V	Units
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage		V <sub>GS</sub>	±20	
Continuous Drain or Source Current (V <sub>GS</sub> > 10V)	TC = 25°C	I <sub>D</sub>	91	A
	TC = 90°C		63	
Pulsed Drain Current ①		I <sub>DM</sub>	363	
Power Dissipation ③	TC = 25°C	P <sub>D</sub>	115	W
	TC = 90°C		60	
Junction & Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Continuous Source Current (Body Diode)		I <sub>S</sub>	91	A
Pulsed Source Current ①		I <sub>SM</sub>	363	

**Thermal Resistance**

Parameter	Symbol	Typ.	Max.	Units
Maximum Junction-to-Ambient ③⑥	R <sub>θJA</sub>	—	50	°C/W
Maximum Junction-to-Case ⑥	R <sub>θJC</sub>	—	1.09	

## Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Units	Conditions
Drain-to-Source Breakdown Voltage	$V_{DSS}$	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	6.9	9.0	m $\Omega$	$V_{GS} = 10V, I_D = 15A$ ②
		—	7.9	10.5		$V_{GS} = 4.5V, I_D = 15A$ ②
Gate Threshold Voltage	$V_{GS(th)}$	1.0	—	3.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Drain-to-Source Leakage Current	$I_{DSS}$	—	—	50	$\mu A$	$V_{DS} = 30V, V_{GS} = 0V$
		—	—	20	$\mu A$	$V_{DS} = 24V, V_{GS} = 0$
		—	—	100		$V_{DS} = 24V, V_{GS} = 0, T_J = 100^\circ C$
Gate-Source Leakage Current	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20V$
Total Gate Charge, Control FET	$Q_G$	—	27	—	nC	$V_{GS} = 5V, I_D = 15A, V_{DS} = 16V$
Total Gate Charge, Synch FET	$Q_G$	—	23	—		$V_{GS} = 5V, V_{DS} < 100mV$
Pre-V <sub>th</sub> Gate-Source Charge	$Q_{GS1}$	—	4.7	—		$V_{DS} = 16V, I_D = 15A$
Post-V <sub>th</sub> Gate-Source Charge	$Q_{GS2}$	—	2.0	—		
Gate to Drain Charge	$Q_{GD}$	—	9.7	—		
Switch Charge ( $Q_{gs2} + Q_{gd}$ )	$Q_{SW}$	—	12	—		
Output Charge	$Q_{OSS}$	—	29	—		$V_{DS} = 16V, V_{GS} = 0$
Gate Resistance	$R_G$	0.8	—	3.1		$\Omega$
Turn-On Delay Time	$t_{d(on)}$	—	10	—	ns	$V_{DD} = 16V$
Rise Time	$t_r$	—	9	—		$I_D = 15A$
Turn-Off Delay Time	$t_{d(off)}$	—	24	—		$V_{GS} = 5.0V$
Fall Time	$t_f$	—	18	—		Clamped Inductive Load
Input Capacitance	$C_{iss}$	—	2672	—	pF	$V_{GS} = 16V, V_{GS} = 0$
Output Capacitance	$C_{oss}$	—	1064	—		
Reverse Transfer Capacitance	$C_{rss}$	—	109	—		

## Source-Drain Rating & Characteristics

Parameter	Symbol	Min	Typ	Max	Units	Conditions
Diode Forward Voltage	$V_{SD}$	—	0.9	1.3	V	$I_S = 15A$ ②, $V_{GS} = 0V$
Reverse Recovery Charge ④	$Q_{rr}$	—	103	—	nC	$di/dt \sim 700A/\mu s$ $V_{DS} = 16V, V_{GS} = 0V, I_F = 15A$
Reverse Recovery Charge (with Parallel Schottky) ④	$Q_{rr(s)}$	—	96	—	nC	$di/dt = 700A/\mu s$ , (with 10BQ040) $V_{DS} = 16V, V_{GS} = 0V, I_F = 15A$

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq 400 \mu s$ ; duty cycle  $\leq 2\%$ .
- ③ When mounted on 1 inch square copper board,  $t < 10$  sec.
- ④ Typ = measured -  $Q_{oss}$
- ⑤ Typical values of  $R_{DS(on)}$  measured at  $V_{GS} = 4.5V$ ,  $Q_G$ ,  $Q_{SW}$  and  $Q_{OSS}$  measured at  $V_{GS} = 5.0V$ ,  $I_F = 15A$ .
- ⑥  $R_\theta$  is measured at  $T_J$  approximately  $90^\circ C$

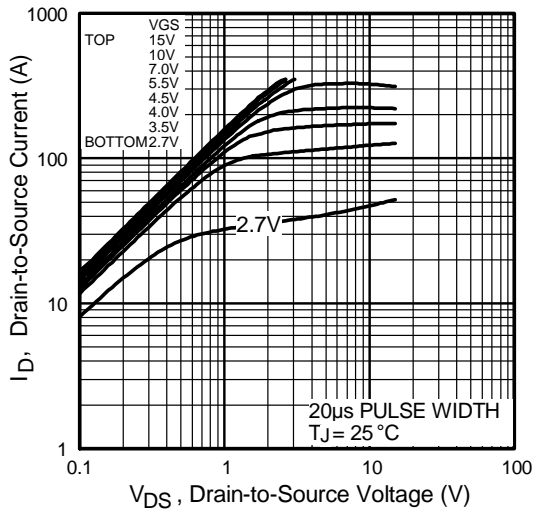


Fig 1. Typical Output Characteristics

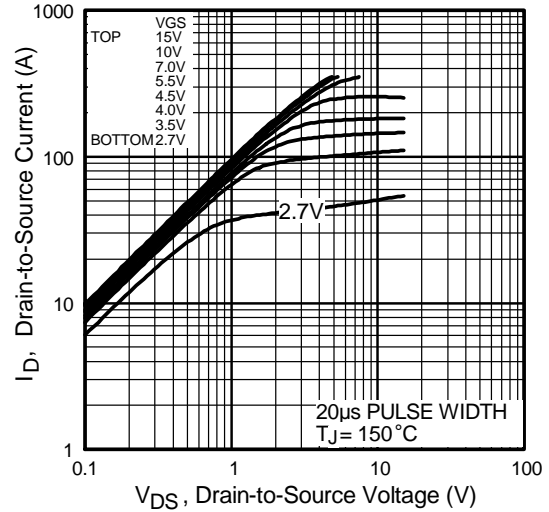


Fig 2. Typical Output Characteristics

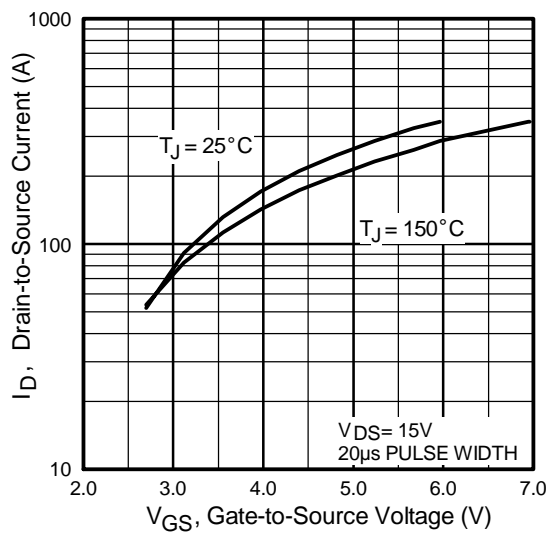


Fig 3. Typical Transfer Characteristics

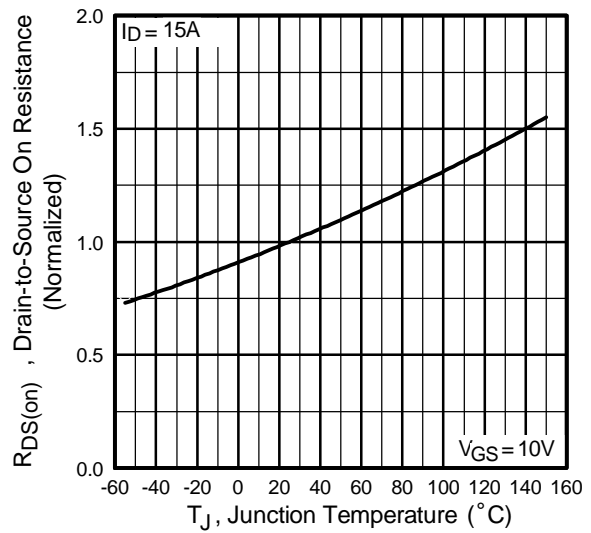
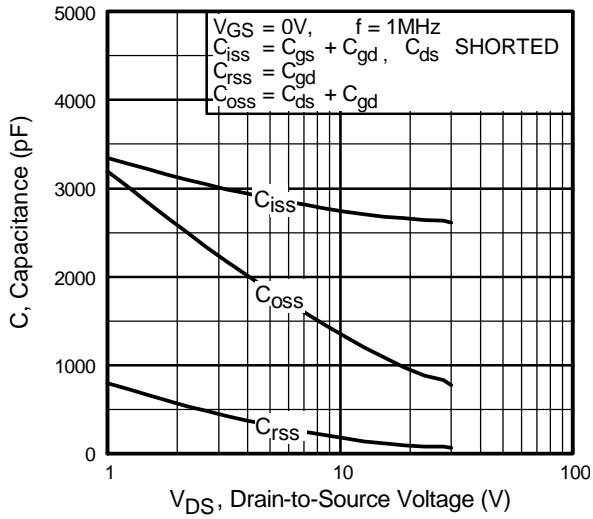
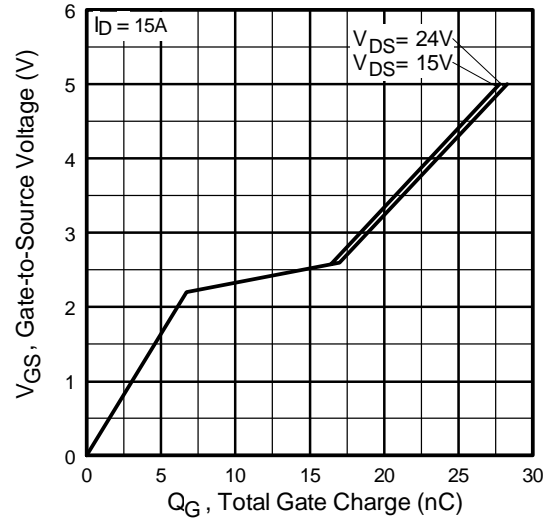


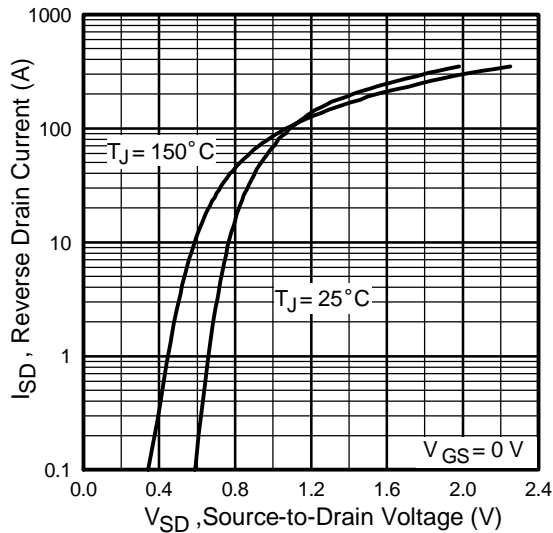
Fig 4. Normalized On-Resistance Vs. Temperature



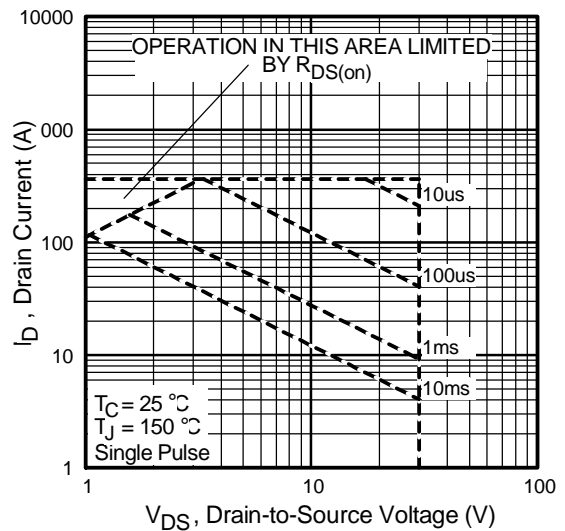
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area

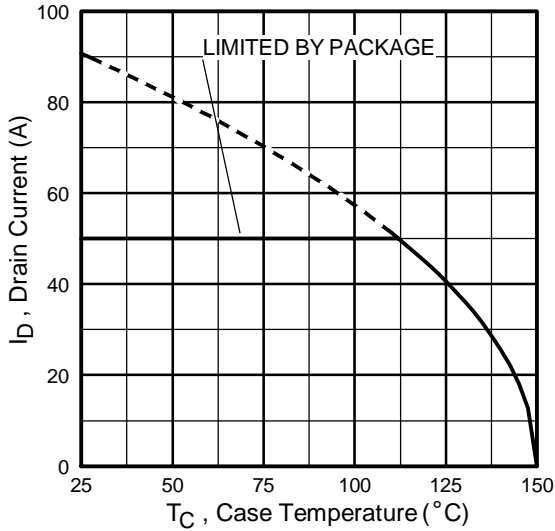


Fig 9. Maximum Drain Current Vs. Case Temperature

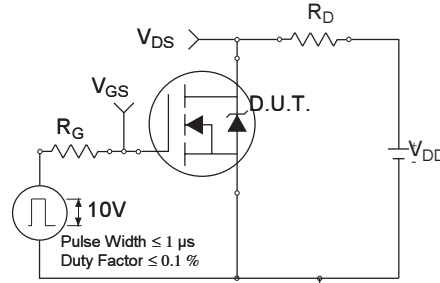


Fig 10a. Switching Time Test Circuit

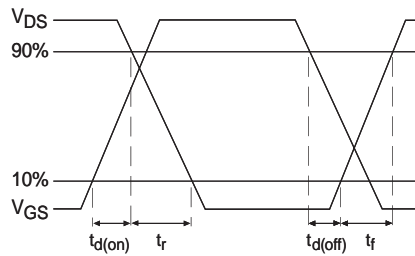


Fig 10b. Switching Time Waveforms

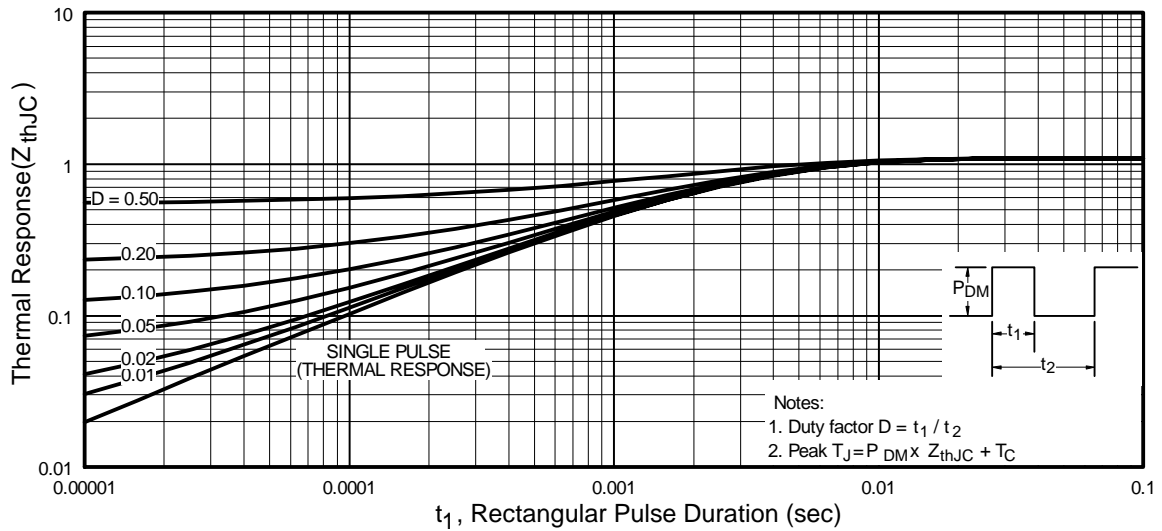
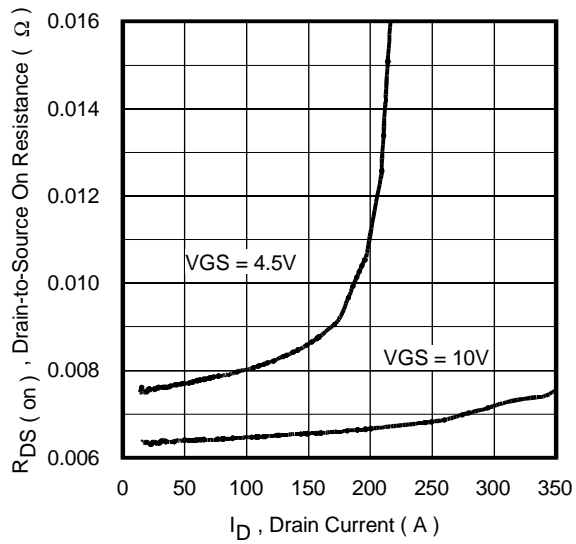
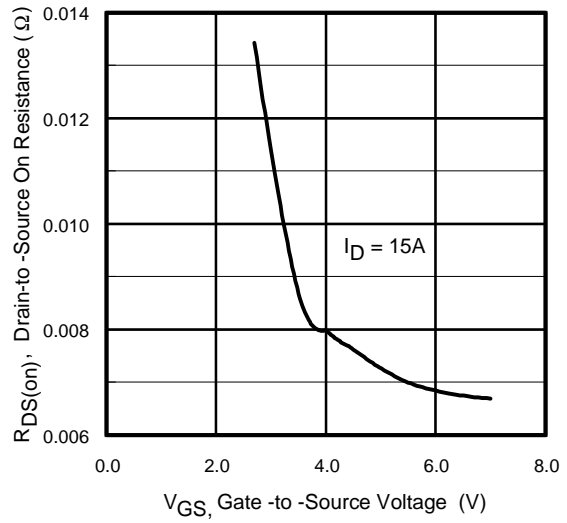


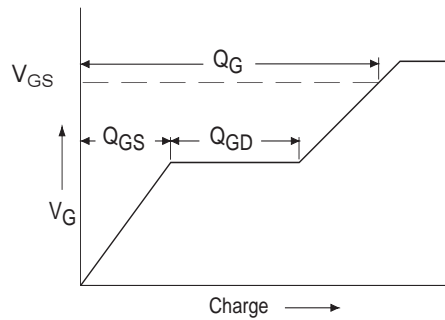
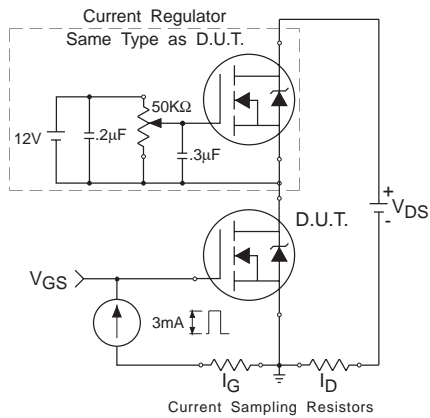
Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Fig 12.** On-Resistance Vs. Drain Current



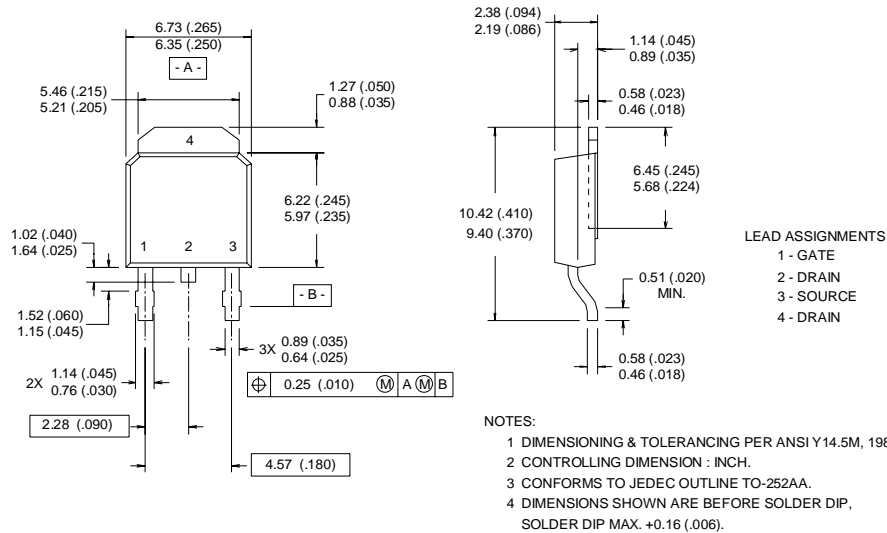
**Fig 13.** On-Resistance Vs. Gate Voltage



**Fig 14a&b.** Basic Gate Charge Test Circuit and Waveform

## D-Pak (TO-252AA) Package Outline

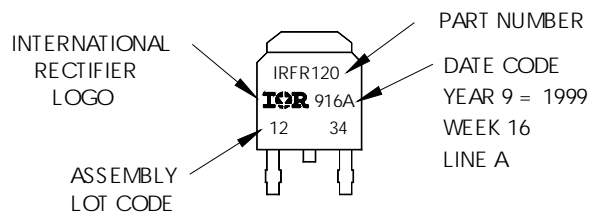
Dimensions are shown in millimeters (inches)



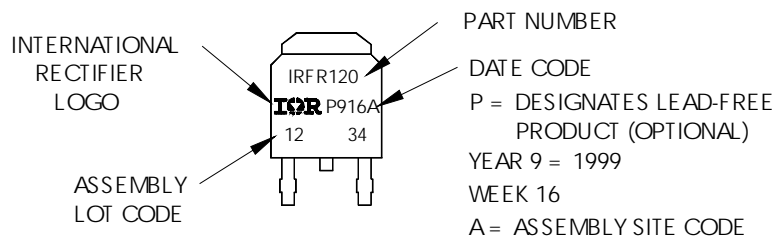
## D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120  
WITH ASSEMBLY  
LOT CODE 1234  
ASSEMBLED ON WW 16, 1999  
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line  
position indicates "Lead-Free"



**OR**

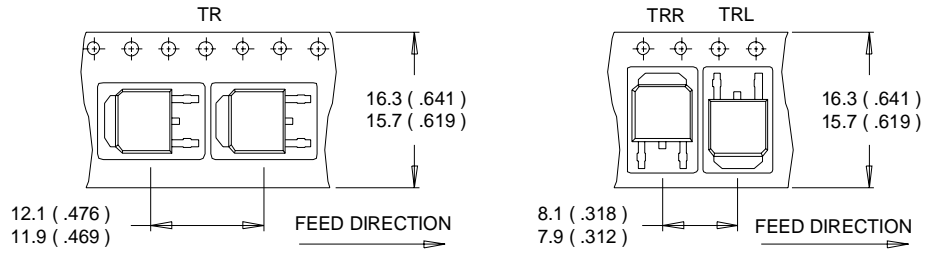


# IRLR8103V

International  
**IR** Rectifier

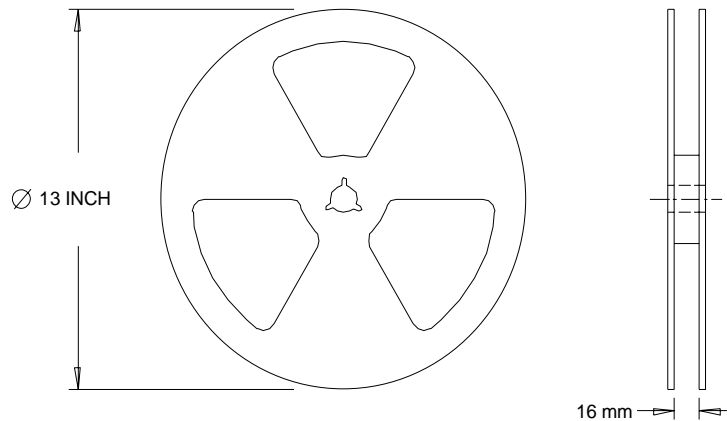
## D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Industrial market.  
Qualification Standards can be found on IR's Web site.

International  
**IR** Rectifier

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